

ABSTRACT OF THE DISCLOSURE

The present invention provides a thermoset conductive ink for use in through hole interconnections or similar electric and electronic applications to provide stable electrical connections. The conductive ink of this invention comprises a thermal curable resin system having an admixture of one or more maleimide, nadimide, or itaconimide containing resins, a comonomer and a catalyst, an electrically conductive material such as silver, copper or silver-coated copper, and optionally an organic solvent.